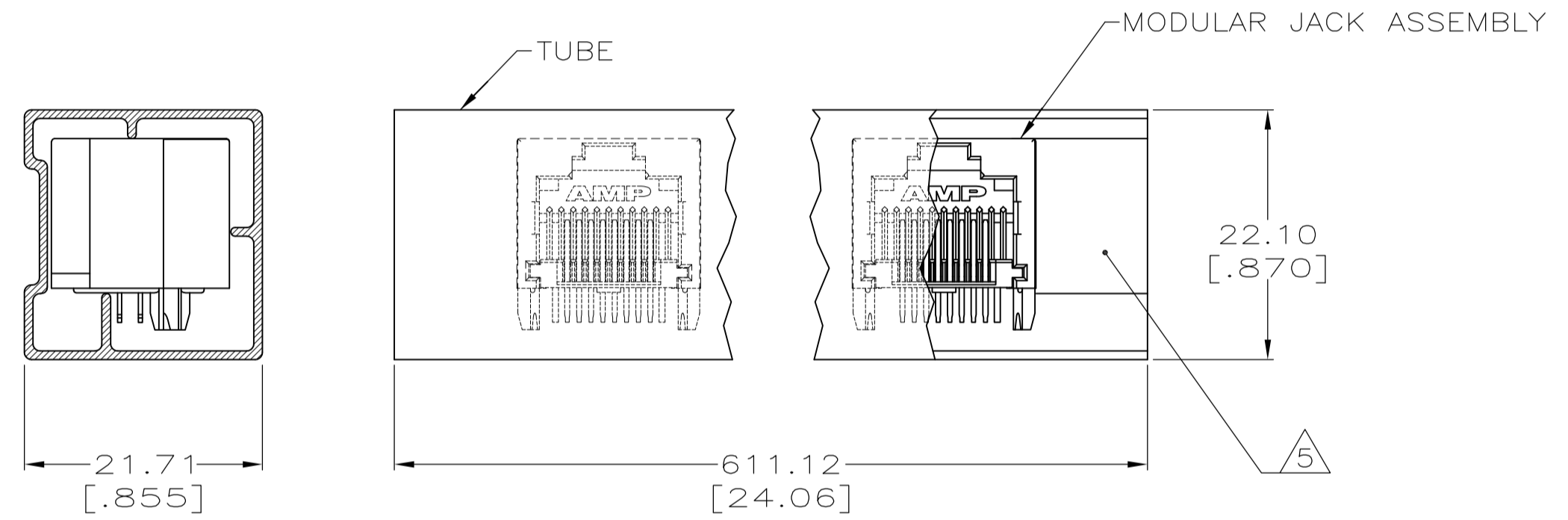
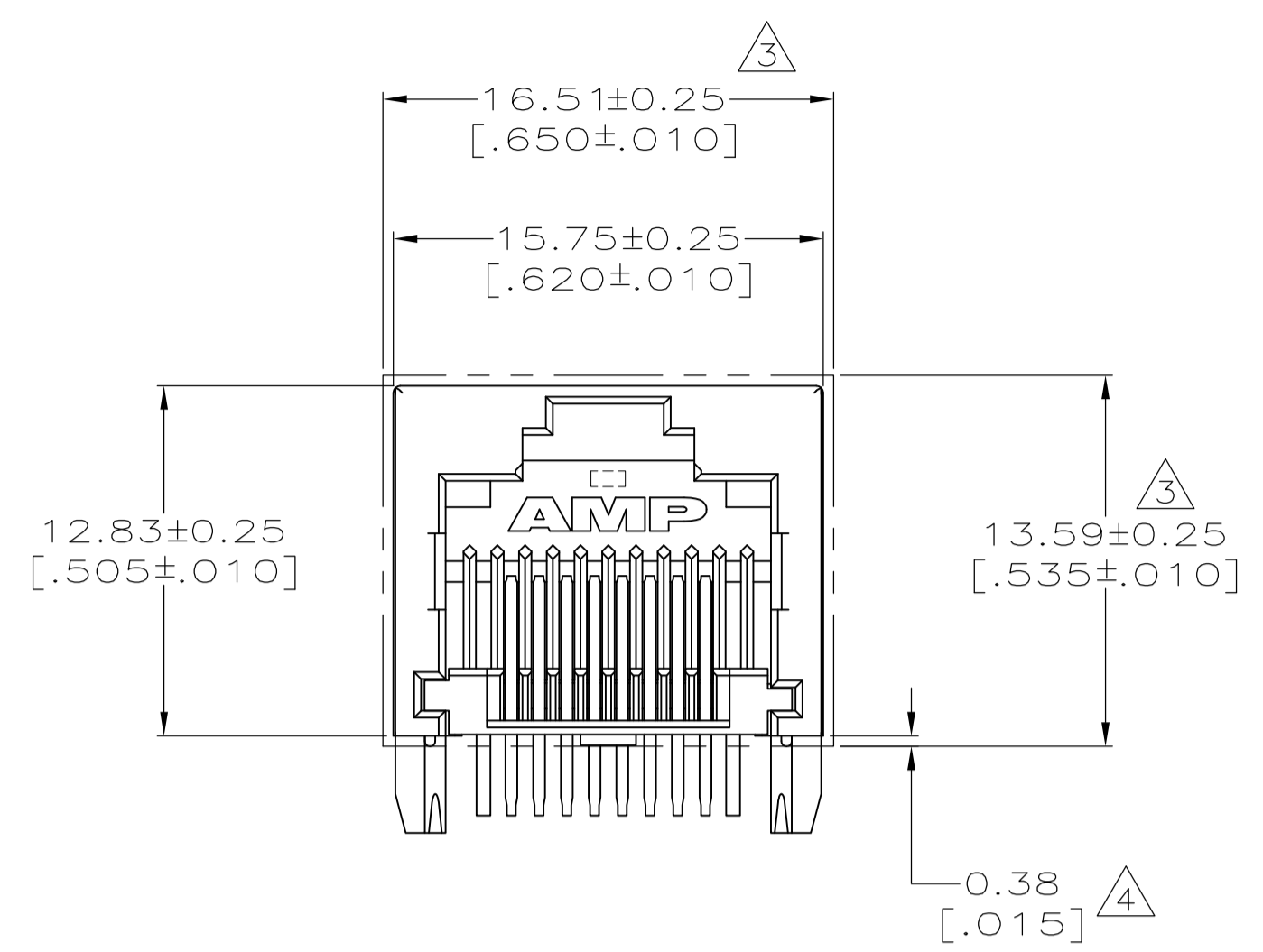
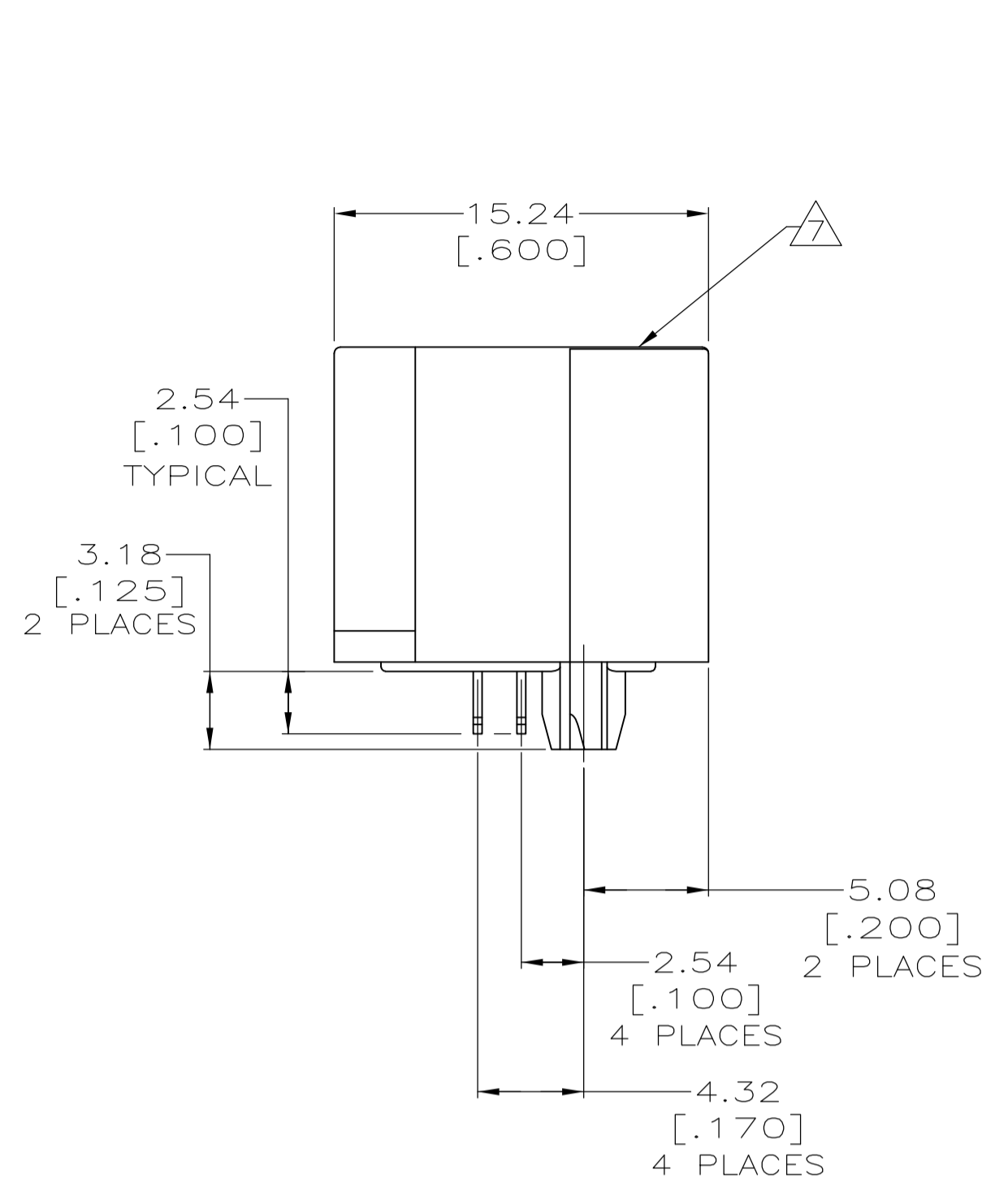
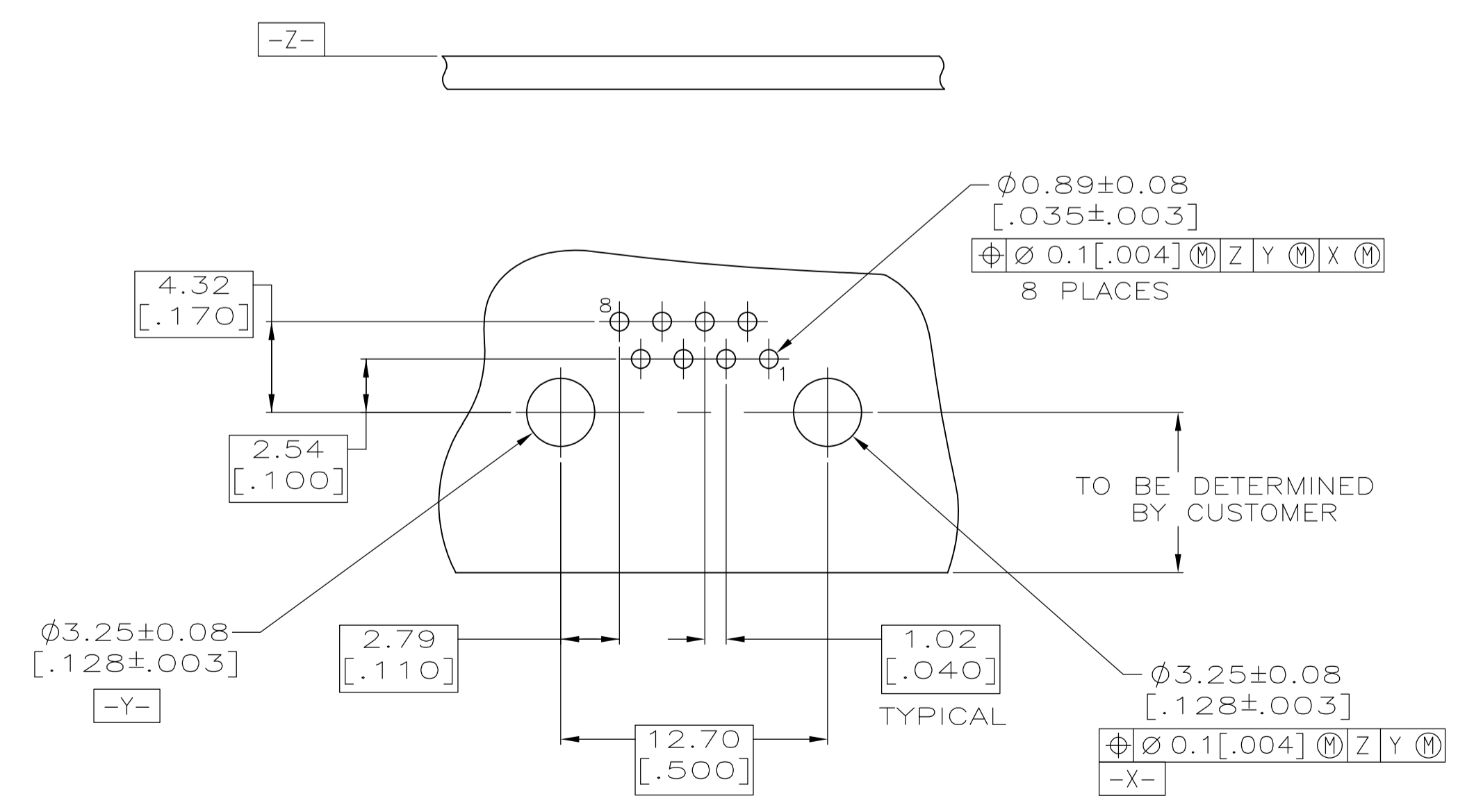


REVISIONS				
P	LTR	DESCRIPTION	DATE	OWN / APPV
E		REVISED PER ECO-12-007519	05AUG2016	AD / SH



- △ MATERIAL:  
HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0; IR REFLOW SOLDERING PROCESS COMPATIBLE.  
TERMINALS - .36[.014] THICK PHOS BRONZE PLATED WITH 3.81µm[.000150] MINIMUM THICK PLATED WITH 1.27µm[.000050] MINIMUM THICK GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm[.000050] MINIMUM THICK NICKEL.
- 2. JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- △ SUGGESTED PANEL OPENING DIMENSIONS.
- △ SUGGESTED CLEARANCE BETWEEN BOTTOM OF CONNECTOR AND BOTTOM PANEL OPENING.
- △ PACKAGED 35 PIECES PER TUBE, SEE DETAIL "A".
- △ 80 PIECES/TRAY, 10 TRAYS/BOX.
- △ MANUFACTURING DATE CODE:  
INK STAMP, LOCATED APPROX. AS SHOWN.  
FIRST 2 DIGITS = LAST 2 DIGITS OF YEAR.  
NEXT 2 DIGITS = MANUFACTURING WORK WEEK.  
LAST DIGIT = DAY OF WEEK WITH SUNDAY = 1.



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT (COMPONENT SIDE)

OBSOLETE	MATTE TIN	△ TUBE	1-406525-3
	MATTE TIN	△ TRAY, PICK & PLACE COMPATIBLE	1-406525-2
	MATTE TIN	TRAY	1-406525-1
OBSOLETE	BRIGHT TIN-LEAD	△ TUBE	406525-3
	BRIGHT TIN-LEAD	△ TRAY, PICK & PLACE COMPATIBLE	406525-2
	BRIGHT TIN-LEAD	TRAY	406525-1
	△ TERMINAL PLATING	PACKAGING	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DIN G. GARRETT 17SEP97	TE Connectivity	
DIMENSIONS: mm [INCHES]		CJK G. GARRETT 17SEP97		
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD M. DERSTINE 17SEP97	NAME	
0 PLC ± -		PRODUCT SPEC	INVERTED MODULAR JACK ASSEMBLY, 1X1	
1 PLC ± -		108-1163-4		
2 PLC ± 0.25[.010]		APPLICATION SPEC		
3 PLC ± 0.13[.005]		114-2154		
4 PLC ± -		WEIGHT 0.000000		
ANGLES ± -		A1 00779 C=406525		
MATERIAL	FINISH	CUSTOMER DRAWING	SCALE 4:1	SHEET 1 OF 1 REV E